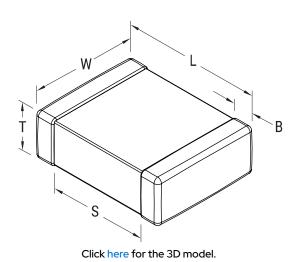




SMD Comm X8G HT150C, Ceramic, 0.047 uF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	1.25mm +/-0.15mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

Packaging Specifications	
В	0.6mm +/-0.35mm
S	2.3mm MIN
Т	1.25mm +/-0.15mm
**	3.211111 / 0.311111

	Specifications		
	Capacitance	0.047 uF	
	Measurement Condition	1 kHz 1.0Vrms	
	Tolerance	20%	
	Voltage DC	200 VDC	
	Dielectric Withstanding Voltage	500 VDC	
	Temperature Range	-55/+150°C	
	Temp. Coefficient	X8G	
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
	Dissipation Factor	0.1% 1 kHz 1.0Vrms	
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
	Insulation Resistance	21.2766 GOhms	

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

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